

Quad 2-Input Exclusive OR Gate

MM74HC86

The MM74HC86 exclusive OR gate utilizes advanced silicon-gate CMOS technology to achieve operating speeds similar to equivalent LS-TTL gates, while maintaining the low power consumption and high noise immunity characteristic of standard CMOS integrated circuits. These gates are fully buffered and have a fanout of 10 LS-TTL loads. The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

- Typical Propagation Delay: 12 ns
- Wide Operating Voltage Range: 2 V – 6 V
- Low Input Current: 1 μA Maximum
- Low Quiescent Current: 40 μA Maximum (74 Series)
- Output Drive Capability: 10 LS-TTL Loads
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

Connection Diagram

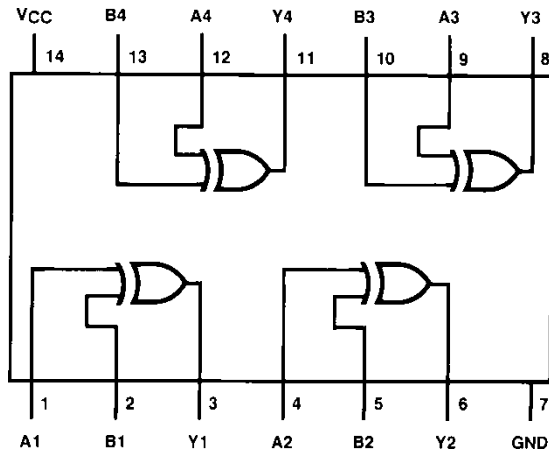


Figure 1. Pin Assignments (Top View)

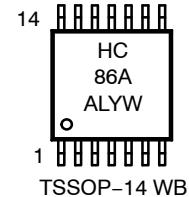
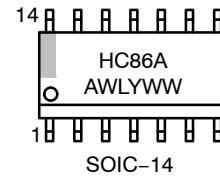
TRUTH TABLE

Inputs		Outputs
A	B	Y (Note1)
L	L	L
L	H	H
H	L	H
H	H	L

1. $Y = A \oplus B = \overline{A}B + A\overline{B}$



MARKING DIAGRAM



HC86A = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MM74HC86

MAXIMUM RATINGS (Note 3)

Symbol	Parameter	Min	Max	Unit
V_{CC}	Supply Voltage	-0.5	7.0	V
V_{IN}	DC Input Voltage	-0.5	$V_{CC} + 0.5$	V
V_{OUT}	DC Output Voltage	-0.5	$V_{CC} + 0.5$	V
I_{IK}, I_{OK}	Clamp Diode Current	±20		mA
I_{OUT}	DC Output Current, per Pin	±25		mA
I_{CC}	DC V_{CC} or GND Current, per Pin	±50		mA
T_{STG}	Storage Temperature Range	-65	+150	°C
T_L	Lead Temperature (Soldering, 10 Seconds)	-	260	°C
P_D	Power Dissipation (Note 3), (Note 2)	-	600	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Power dissipation temperature derating – plastic “N” package: -12 mW/°C from 65°C to 85°C.

3. S.O. package only 500 mW.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply Voltage		2	6	V
V_{IN}, V_{OUT}	DC Input or Output Voltage		0	V_{CC}	V
T_A	Operating Temperature Range		-55	+125	°C
t_r, t_f	Input Rise or Fall Times	$V_{CC} = 2.0\text{ V}$	-	1000	ns
		$V_{CC} = 4.5\text{ V}$	-	500	
		$V_{CC} = 6.0\text{ V}$	-	400	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

MM74HC86

DC CHARACTERISTICS (Note 4)

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C		T _A = -40°C	T _A = -55°C	Unit
				Typ	Guaranteed Limits			
V _{IH}	Minimum HIGH Level Input Voltage		2.0	-	1.5	1.5	1.5	V
			4.5	-	3.15	3.15	3.15	
			6.0	-	4.2	4.2	4.2	
V _{IL}	Maximum LOW Level Input Voltage		2.0	-	0.5	0.5	0.5	V
			4.5	-	1.35	1.35	1.35	
			6.0	-	1.8	1.8	1.8	
V _{OH}	Minimum HIGH Level Output Voltage	V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 20 μA	2.0	2.0	1.9	1.9	1.9	V
			4.5	4.5	4.4	4.4	4.4	
			6.0	6.0	5.9	5.9	5.9	
		V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 4.0 mA	4.5	4.2	3.98	3.84	3.70	
		V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 5.2 mA	6.0	5.7	5.48	5.34	5.20	
V _{OL}	Maximum LOW Level Output Voltage	V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 20 μA	2.0	0	0.1	0.1	0.1	V
			4.5	0	0.1	0.1	0.1	
			6.0	0	0.1	0.1	0.1	
		V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 4.0 mA	4.5	0.2	0.26	0.33	0.4	
		V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 5.2 mA	6.0	0.2	0.26	0.33	0.4	
I _{IN}	Maximum Input Current	V _{IN} = V _{CC} or GND	6.0	-	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND, I _{OUT} = 0 mA	6.0	-	2.0	20	40	μA

4. For a power supply of 5 V ±10% the worst-case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst-case V_{IH} and V_{IL} occur at V_{CC} = 5.5 V and 4.5 V, respectively. (The V_{IH} values at 5 V and 5.5 V are 3.5 V and 3.85 V, respectively.) The worst-case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occurs for CMOS at the higher voltage, so the 6.0 V values should be used.

AC CHARACTERISTICS (C_L = 50 pF, t_r = t_f = 6 ns (unless otherwise specified))

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C		T _A = -40°C	T _A = -55°C	Unit
				Typ	Guaranteed Limits			
t _{PHL} , t _{PLH}	Maximum Propagation Delay	C _L = 15 pF, t _r = t _f = 6 ns	5.0	12	-	20	-	ns
t _{PHL} , t _{PLH}	Maximum Propagation Delay	C _L = 50 pF, t _r = t _f = 6 ns	2.0	60	120	151	179	ns
			4.5	12	24	30	36	
			6.0	10	20	26	30	
t _{TLH} , t _{THL}	Maximum Output Rise and Fall Time		2.0	30	75	95	110	ns
			4.5	8	15	19	22	
			6.0	7	13	16	19	
C _{PD}	Power Dissipation Capacitance (per Gate) (Note 5)			25	-	-	-	pF
C _{IN}	Maximum Input Capacitance			5	10	10	10	pF

5. C_{PD} determines the no-load dynamic power consumption, P_D = C_{PD} V_{CC}² f + I_{CC} V_{CC}, and the no load dynamic current consumption, I_S = C_{PD} V_{CC} f + I_{CC}.

MM74HC86

ORDERING INFORMATION

Part Number	Package	Shipping†
MM74HC86M	SOIC-14, Case 751A-03 (Pb-Free, Halide Free)	55 Units / Tube
MM74HC86MTC	TSSOP-14, Case 948G-01 (Pb-Free, Halide Free)	96 Units / Tube
MM74HC86MX	SOIC-14, Case 751EF (Pb-Free, Halide Free)	2500 / Tape & Reel
MM74HC86MTCX	TSSOP-14, Case 948G-01 (Pb-Free, Halide Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

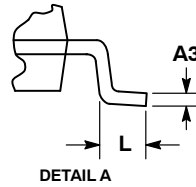
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-14 NB
CASE 751A-03
ISSUE L

DATE 03 FEB 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. NO CONNECTION
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 2:
 CANCELLED

STYLE 3:
 PIN 1. NO CONNECTION
 2. ANODE
 3. ANODE
 4. NO CONNECTION
 5. ANODE
 6. NO CONNECTION
 7. ANODE
 8. ANODE
 9. ANODE
 10. NO CONNECTION
 11. ANODE
 12. ANODE
 13. NO CONNECTION
 14. COMMON CATHODE

STYLE 4:
 PIN 1. NO CONNECTION
 2. CATHODE
 3. CATHODE
 4. NO CONNECTION
 5. CATHODE
 6. NO CONNECTION
 7. CATHODE
 8. CATHODE
 9. CATHODE
 10. NO CONNECTION
 11. CATHODE
 12. CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 5:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. COMMON ANODE
 8. COMMON CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 6:
 PIN 1. CATHODE
 2. CATHODE
 3. CATHODE
 4. CATHODE
 5. CATHODE
 6. CATHODE
 7. CATHODE
 8. ANODE
 9. ANODE
 10. ANODE
 11. ANODE
 12. ANODE
 13. ANODE
 14. ANODE

STYLE 7:
 PIN 1. ANODE/CATHODE
 2. COMMON ANODE
 3. COMMON CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. COMMON CATHODE
 12. COMMON ANODE
 13. ANODE/CATHODE
 14. ANODE/CATHODE

STYLE 8:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. COMMON ANODE
 8. COMMON ANODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. NO CONNECTION
 12. ANODE/CATHODE
 13. ANODE/CATHODE
 14. COMMON CATHODE

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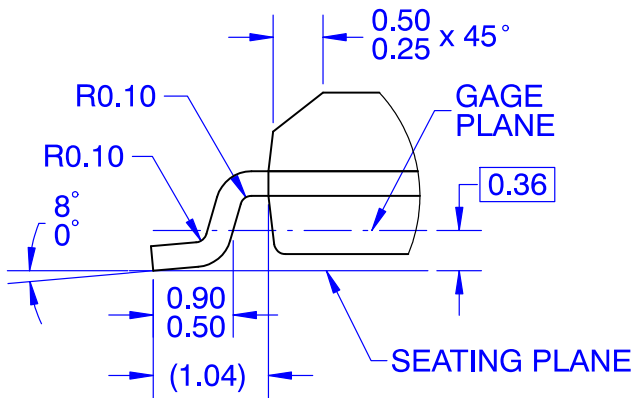
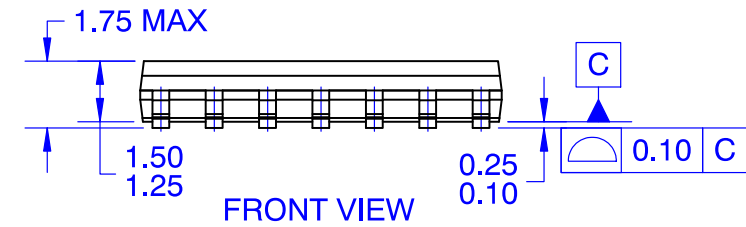
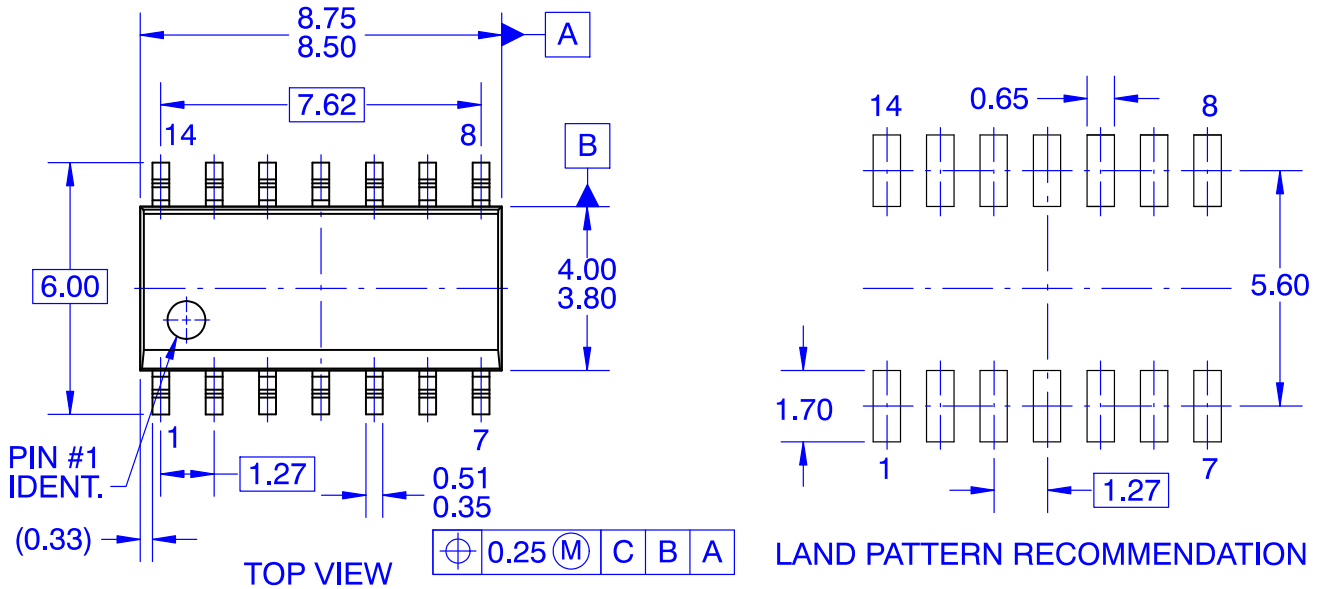
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



SOIC14
CASE 751EF
ISSUE O

DATE 30 SEP 2016



DETAIL A
SCALE 16 : 1

NOTES:

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TSSOP-14 WB
CASE 948G
ISSUE C

DATE 17 FEB 2016

SCALE 2:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

GENERIC MARKING DIAGRAM*

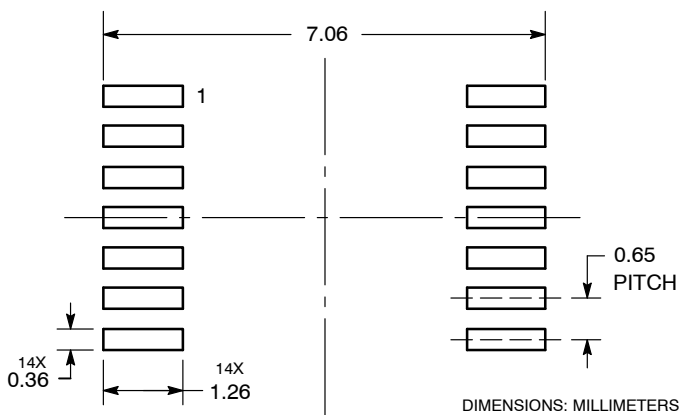


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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